

# MA2SP06

## Silicon planar type

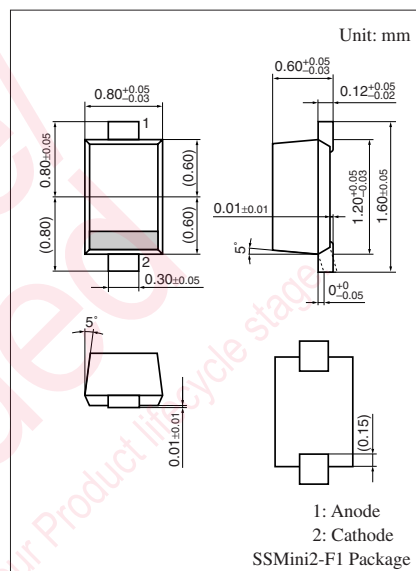
For high frequency switch

### ■ Features

- Low terminal capacitance:  $C_t \leq 0.6$  pF
- Low forward dynamic resistance:  $r_f \leq 1.2$   $\Omega$

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	60	V
Forward current	$I_F$	100	mA
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

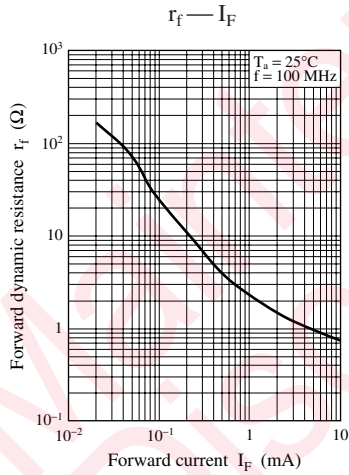
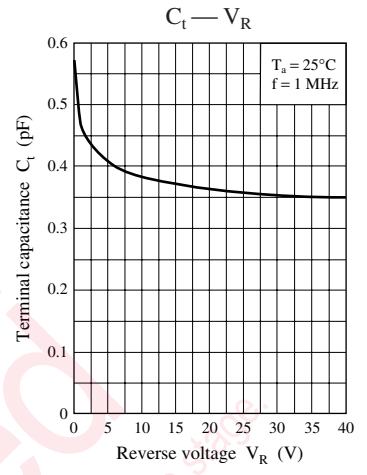
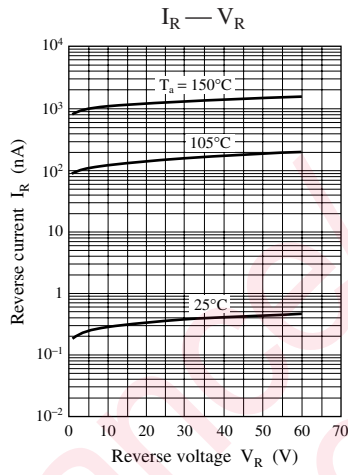
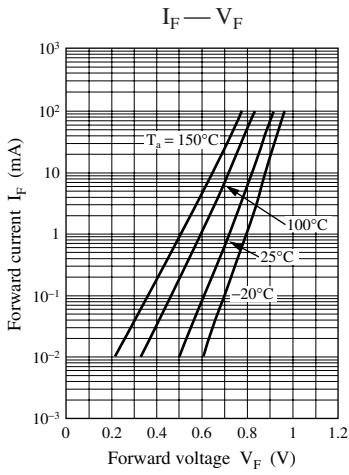


Marking Symbol: 7P

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 10$ mA		0.85	1.0	V
Reverse current	$I_R$	$V_R = 60$ V		1.0	100	nA
Terminal capacitance	$C_t$	$V_R = 1$ V, $f = 1$ MHz		0.45	0.6	pF
Forward dynamic resistance	$r_f$	$I_F = 10$ mA, $f = 100$ MHz		0.80	1.2	$\Omega$

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.



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 planned maintenance type  
 maintenance type  
 planned discontinued type  
 discontinued type  
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